

Title (en)
VAPOR PHASE CONNECTION TECHNIQUES

Title (de)
VERBINDUNGSTECHNIK IN DER GASPHASE

Title (fr)
TECHNIQUES DE CONNEXION EN PHASE VAPEUR

Publication
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Application
EP 00954052 A 20000811

Priority
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• US 14823399 P 19990811

Abstract (en)
[origin: WO0111662A2] Electrical connections are made between a pair of elements (32, 38) disposed on opposite side of a hole (28) extending through a dielectric layer (20) by evaporating a conductive material (40) such as a metal having high vapor pressure within the hole while maintaining the hole in a substantially sealed condition. The process may be performed simultaneously to form numerous connections within a microelectronic unit as, for example, within a multilayer circuit panel.

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B05D 5/12

IPC 8 full level
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H01L 21/486 (2013.01 - EP); **H05K 3/40** (2013.01 - KR); **H05K 3/4076** (2013.01 - EP); **H01L 2924/0002** (2013.01 - EP); **H05K 2203/083** (2013.01 - EP); **H05K 2203/085** (2013.01 - EP); **H05K 2203/1105** (2013.01 - EP)

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